

# Model Name: EBA35001-10

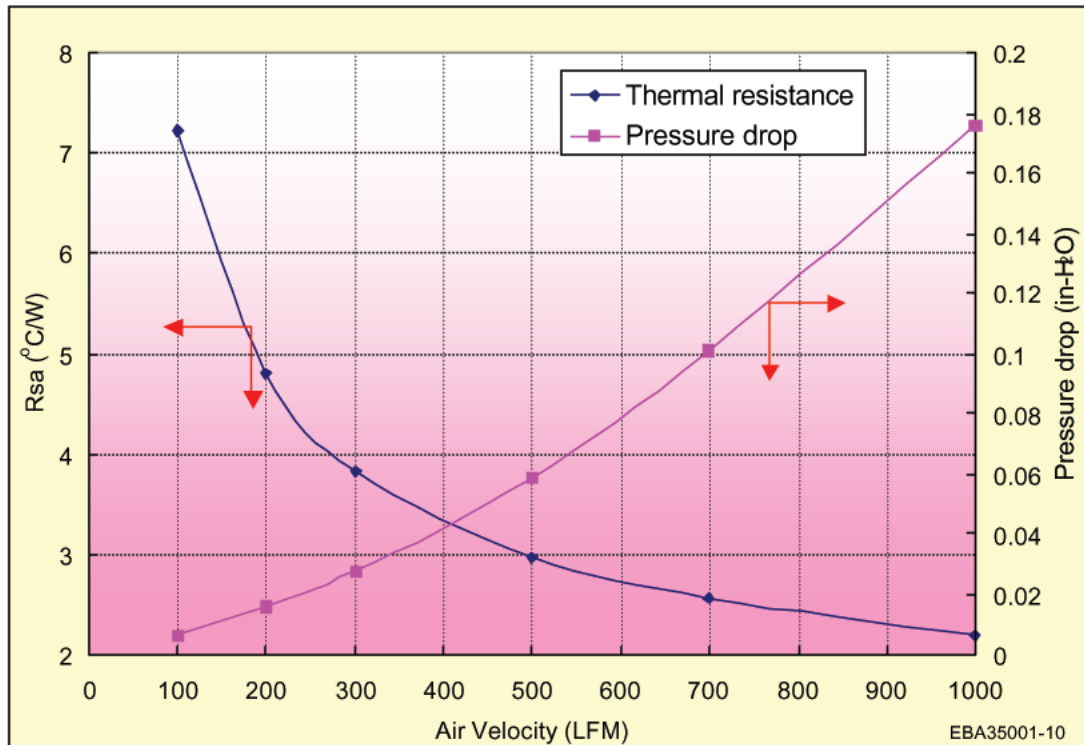
## BGA Heat Sink For 35x35 Chip set

### \*Specification:

1. Material: Aluminum 6063
2. Weight: 12 gm
3. Technology: Extrusion
4. Finish: Black Anodize
5. Heat Sink Dimension:  
34.6\*34.5\*9.8mm
6. Copper package and Moulding compound package available
7. Heat Source size: Uniform



### \*Performance Data:



**AMERICAN THERMAL PRODUCTS**

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